



Note:

1. Material:

1.1 Housing: High temperature thermoplastic with g. f, UL94v-0

1.2 Contact: copper alloy,  $t=0.20\text{mm}$

1.3 Shell: copper alloy,  $t=0.25\text{mm}$

2. Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding

voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05

Kgf Min. after 10000 insertion/extraction cycles

2.7 Temperature range:  $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$

RECOMMENDED PCB LAYOUT

设计 DRAW BY	杨帆	审核 DISCUSS BY	
校对 DISCUSS BY		比例 SCALE	2:1

HDC有限公司

图名 DRAWING NO	MICRO USB B TYPE 沉板 DIP	图号 SHEET NO	021	日期 DATE	2009.3.16
客户 VERSION		数量 QUAN		备注 REMARK	
				版次 REMARK	张号 SHEET
					1/1